

FIG. 2 is a cross-sectional view of a device assembly 102. The assembly includes a top layer 104, a middle layer 210, and a bottom layer 220. A central component 218 is positioned between the top and middle layers. A series of vertical structures 212, 214, 216, and 218 are shown. A bracket 102 groups the central components. An arrow 208 points to the central region. Other labels include 222, 224, 226, and 228.

A cross-sectional view of a multi-layered electronic assembly 300. The assembly includes a top layer 304 with a central rectangular component 318. Below this is a layer 310 containing a series of vertical structures 312 and 314. A central block 330 is positioned below these structures. The bottom layer 302 consists of a base 332 with multiple rectangular features 331 and 326. A central vertical structure 328 is also present. A bracket on the right side of the diagram groups the bottom layer components under the label 302. An arrow points from the label 300 to the top left corner of the assembly.

FIG. 3

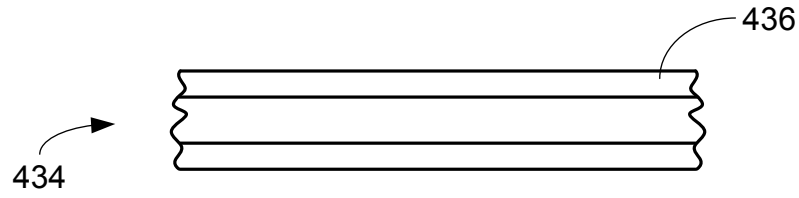


FIG. 4

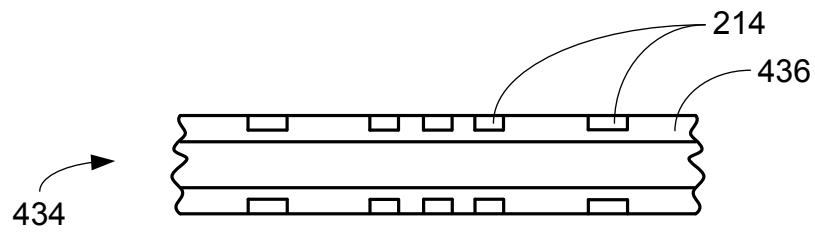


FIG. 5

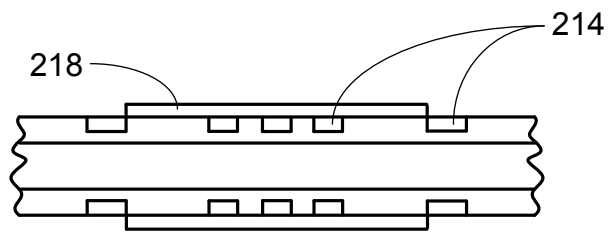


FIG. 6

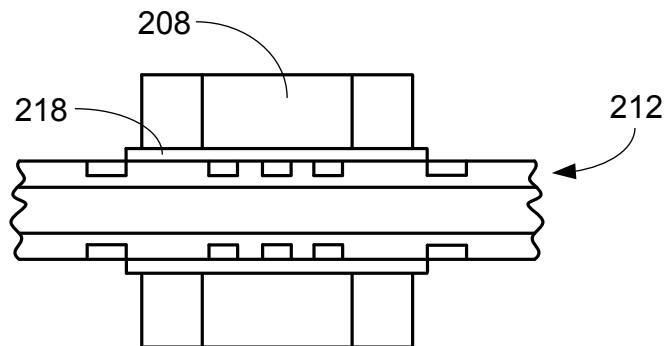


FIG. 7

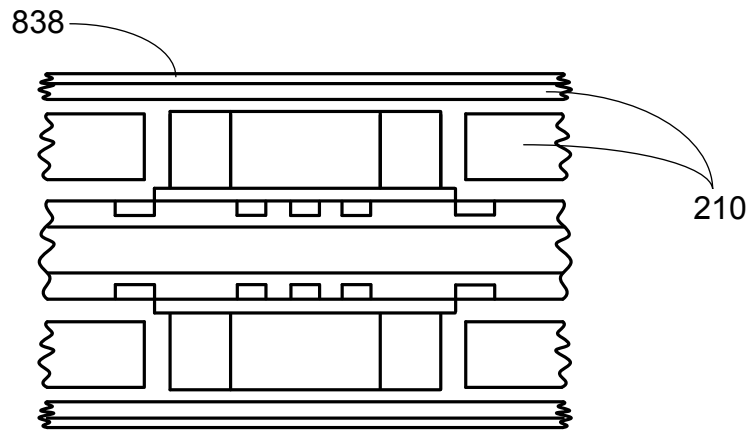


FIG. 8

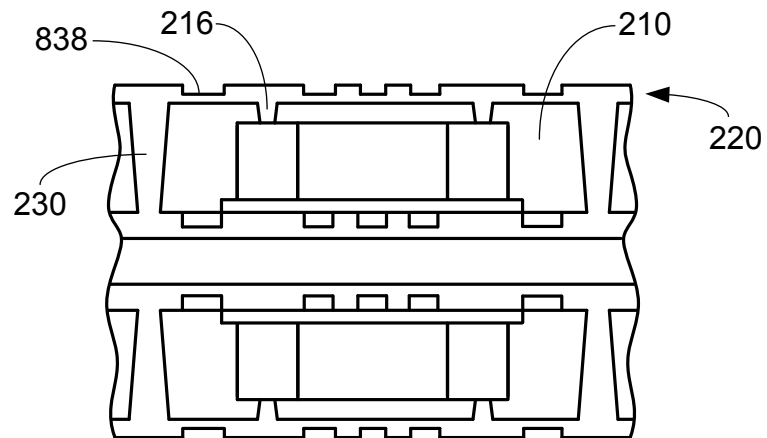


FIG. 9

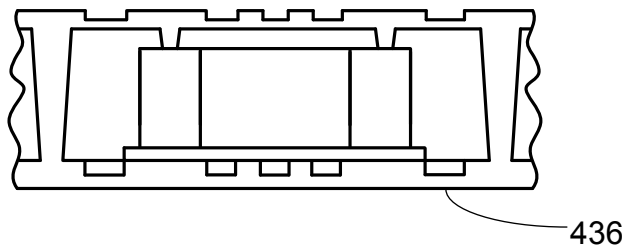


FIG. 10

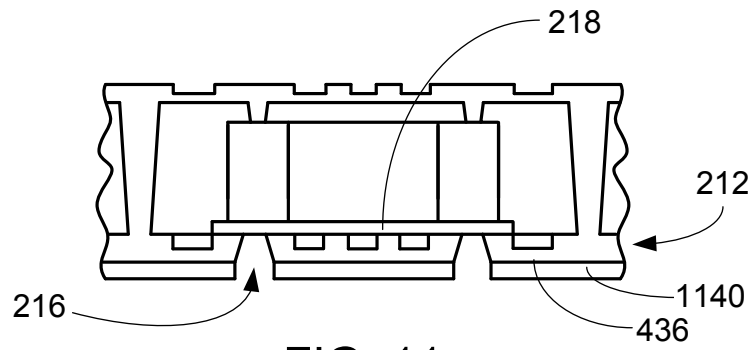


FIG. 11

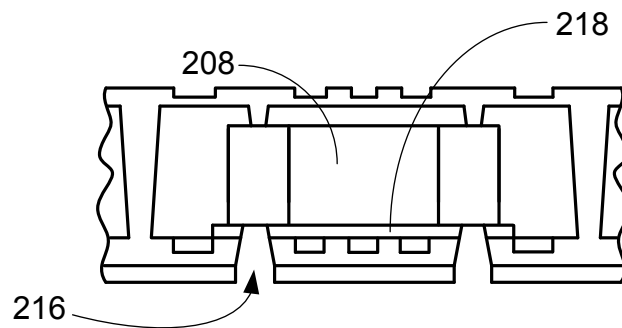


FIG. 12

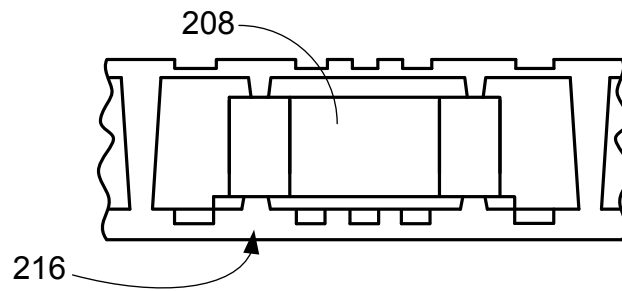


FIG. 13

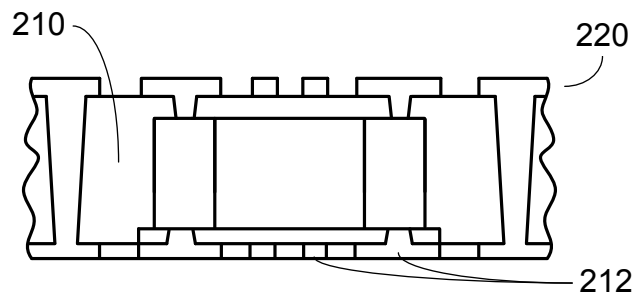


FIG. 14

5/7

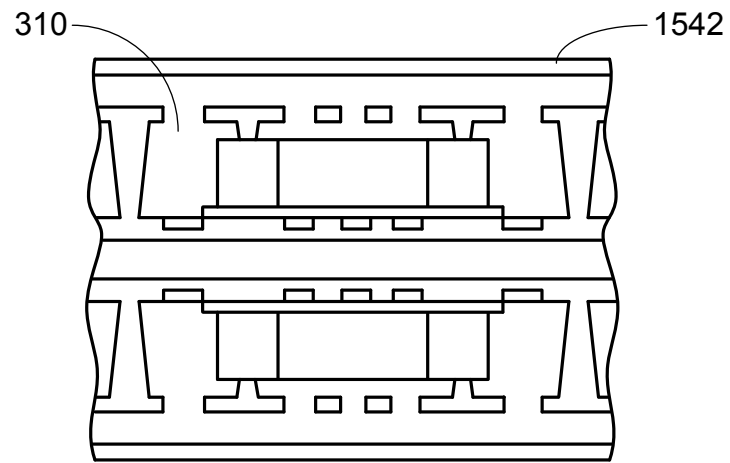


FIG. 15

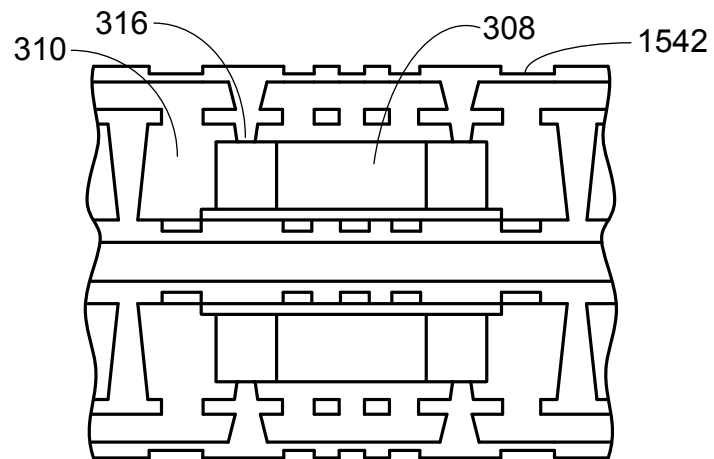


FIG. 16

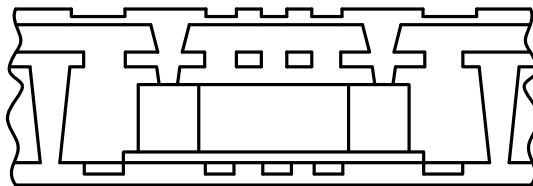


FIG. 17

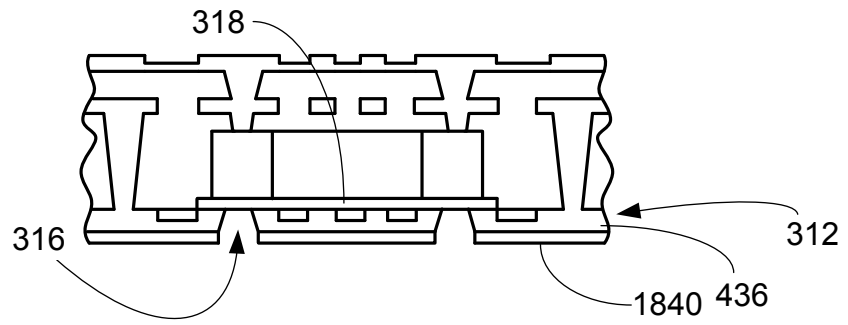


FIG. 18

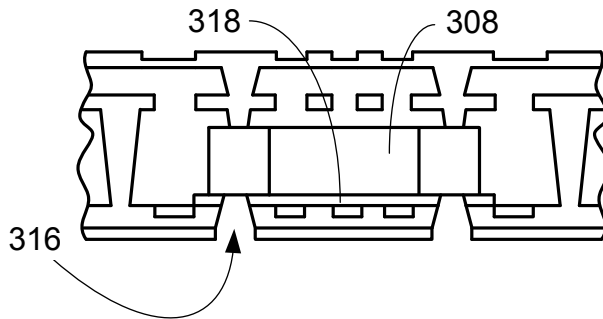


FIG. 19

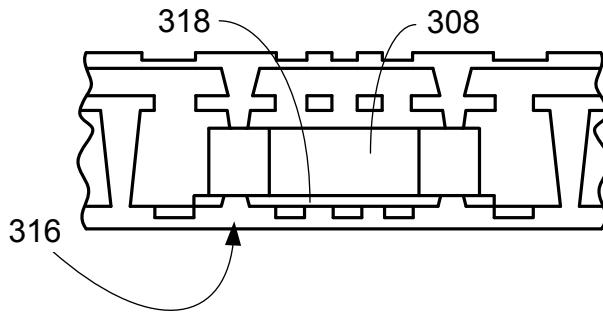


FIG. 20

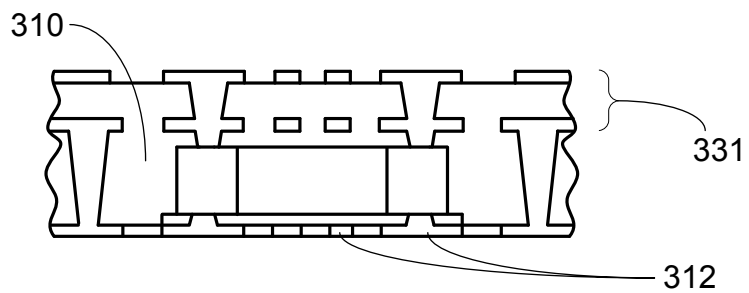


FIG. 21

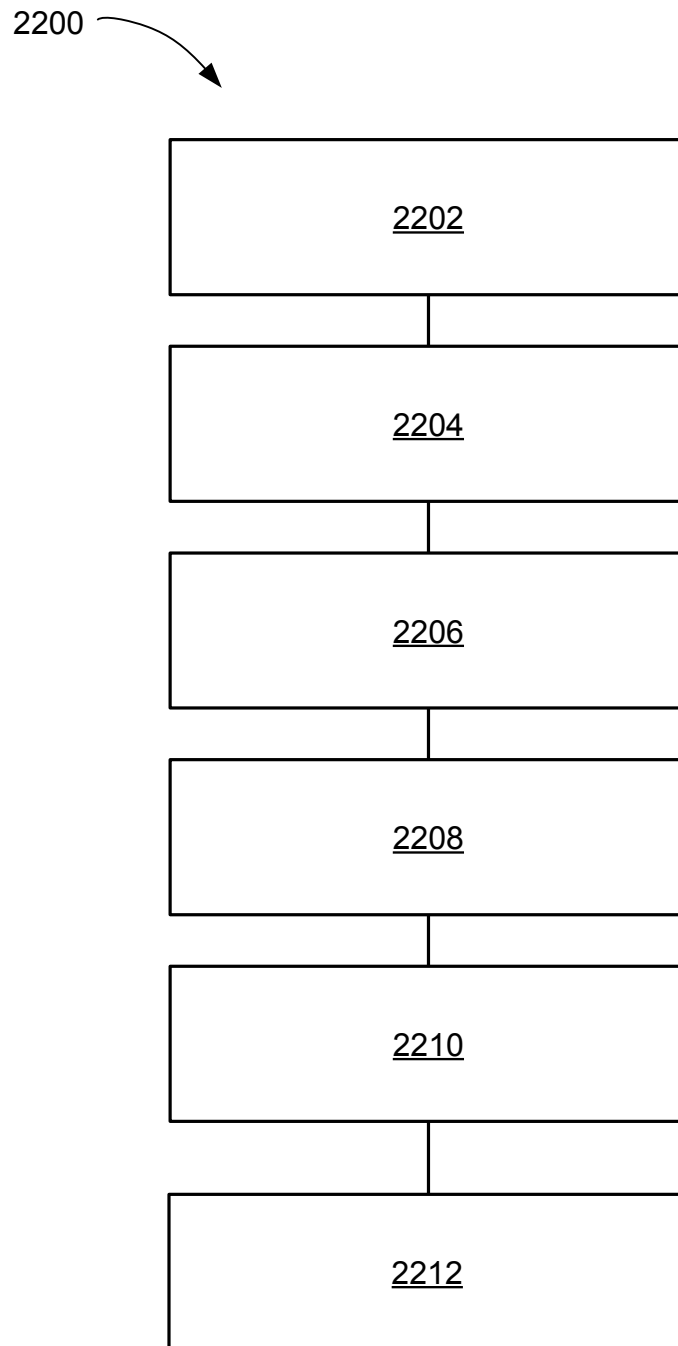


FIG. 22